

## SOT-23-6L Plastic-Encapsulate MOSFETS

### NCE8205 Dual N-Channel MOSFET

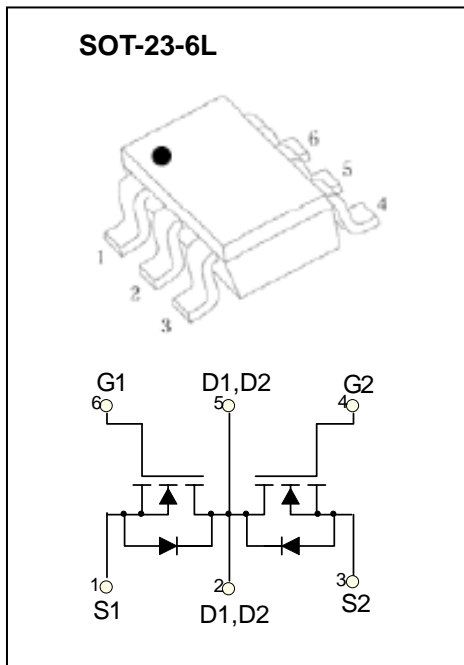
#### FEATURE

- TrenchFET Power MOSFET
- Excellent  $R_{DS(on)}$
- Low Gate Charge
- High Power and Current Handling Capability
- Surface Mount Package

#### APPLICATION

- Battery Protection
- Load Switch
- Power Management

#### MARKING



#### ABSOLUTE MAXIMUM RATINGS ( $T_a=25^{\circ}\text{C}$ unless otherwise noted)

| Parameter                                                        | Symbol          | Value    | Unit                 |
|------------------------------------------------------------------|-----------------|----------|----------------------|
| Drain-Source Voltage                                             | $V_{DS}$        | 19       | V                    |
| Gate-Source Voltage                                              | $V_{GS}$        | $\pm 10$ | V                    |
| Continuous Drain Current                                         | $I_D$           | 6        | A                    |
| Pulsed Drain Current (note 1)                                    | $I_{DM}$        | 25       | A                    |
| Thermal Resistance from Junction to Ambient (note 2)             | $R_{\theta JA}$ | 357      | $^{\circ}\text{C/W}$ |
| Junction Temperature                                             | $T_J$           | 150      | $^{\circ}\text{C}$   |
| Storage Temperature                                              | $T_{STG}$       | -55~+150 | $^{\circ}\text{C}$   |
| Lead Temperature for Soldering Purposes(1/8" from case for 10 s) | $T_L$           | 260      | $^{\circ}\text{C}$   |

**ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

| Parameter                                 | Symbol               | Test Condition                                                                          | Min  | Typ | Max  | Unit |
|-------------------------------------------|----------------------|-----------------------------------------------------------------------------------------|------|-----|------|------|
| <b>STATIC CHARACTERISTICS</b>             |                      |                                                                                         |      |     |      |      |
| Drain-source breakdown voltage            | V <sub>(BR)DSS</sub> | V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA                                             | 19   |     |      | V    |
| Zero gate voltage drain current           | I <sub>DSS</sub>     | V <sub>DS</sub> =18V, V <sub>GS</sub> = 0V                                              |      |     | 1    | μA   |
| Gate-body leakage current                 | I <sub>GSS</sub>     | V <sub>GS</sub> =±10V, V <sub>DS</sub> = 0V                                             |      |     | ±100 | nA   |
| Gate threshold voltage (note 3)           | V <sub>GS(th)</sub>  | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                | 0.45 |     | 1.2  | V    |
| Drain-source on-resistance (note 3)       | R <sub>DS(on)</sub>  | V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A                                               |      |     | 27   | mΩ   |
|                                           |                      | V <sub>GS</sub> =2.5V, I <sub>D</sub> =5A                                               |      |     | 37   | mΩ   |
| Forward tranconductance (note 3)          | g <sub>FS</sub>      | V <sub>DS</sub> =5V, I <sub>D</sub> =4.5A                                               |      | 10  |      | S    |
| Diode forward voltage (note 3)            | V <sub>SD</sub>      | I <sub>S</sub> =1.25A, V <sub>GS</sub> = 0V                                             |      |     | 1.2  | V    |
| <b>DYNAMIC CHARACTERISTICS (note4)</b>    |                      |                                                                                         |      |     |      |      |
| Input Capacitance                         | C <sub>iss</sub>     | V <sub>DS</sub> =8V, V <sub>GS</sub> =0V, f =1MHz                                       |      | 800 |      | pF   |
| Output Capacitance                        | C <sub>oss</sub>     |                                                                                         |      | 155 |      | pF   |
| Reverse Transfer Capacitance              | C <sub>rss</sub>     |                                                                                         |      | 125 |      | pF   |
| <b>SWITCHING CHARACTERISTICS (note 4)</b> |                      |                                                                                         |      |     |      |      |
| Turn-on delay time                        | t <sub>d(on)</sub>   | V <sub>DD</sub> =10V, V <sub>GS</sub> =4V,<br>I <sub>D</sub> =1A, R <sub>GEN</sub> =10Ω |      | 18  |      | ns   |
| Turn-on rise time                         | t <sub>r</sub>       |                                                                                         |      | 5   |      | ns   |
| Turn-off delay time                       | t <sub>d(off)</sub>  |                                                                                         |      | 43  |      | ns   |
| Turn-off fall time                        | t <sub>f</sub>       |                                                                                         |      | 20  |      | ns   |
| Total Gate Charge                         | Q <sub>g</sub>       | V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A                         |      | 11  |      | nC   |
| Gate-Source Charge                        | Q <sub>gs</sub>      |                                                                                         |      | 2.3 |      | nC   |
| Gate-Drain Charge                         | Q <sub>gd</sub>      |                                                                                         |      | 2.5 |      | nC   |

**Notes :**

- 1.Repetitive rating: Pluse width limited by maximum junction temperature
- 2.Surface Mounted on FR4 board, t≤10 sec.
3. Pulse test : Pulse width≤300μs, duty cycle≤2%.
4. Guaranteed by design, not subject to production.